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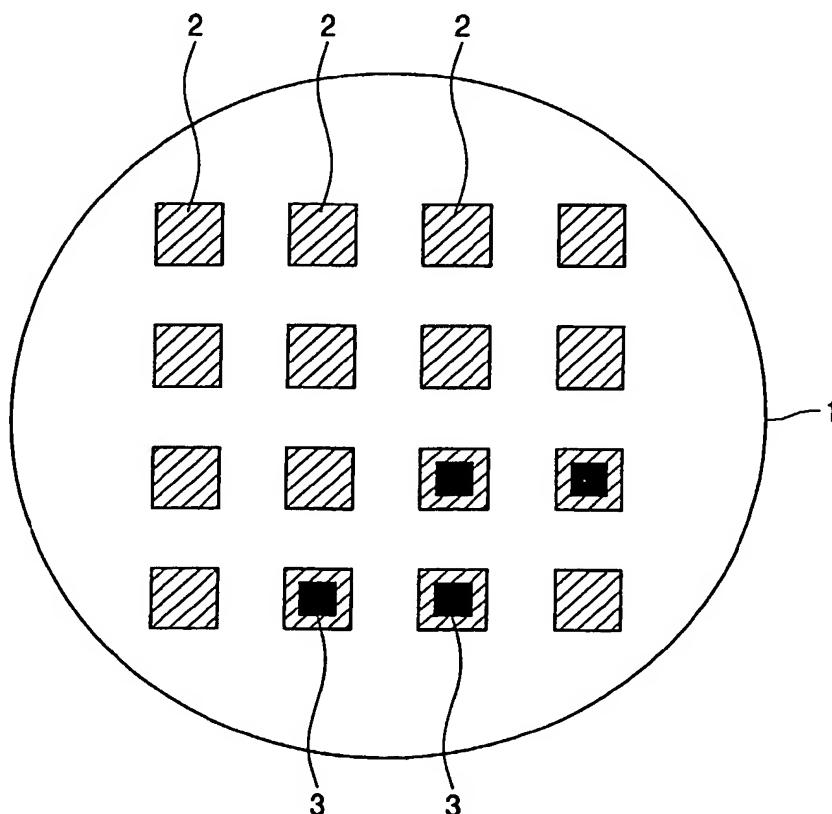
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(54) Title: **SUPPORT PLATE FOR SEMICONDUCTOR COMPONENTS**



(57) Abstract: The present invention relates to a support plate (1), preferably made from glass, granite or ceramic, for supporting components (3), in particular ICs or other semiconductor components. The top face of the support plate (1) is at least partially roughened (roughened areas (2)), resulting in a roughness Ra of preferably about 0.3 micrometer. Further, the present invention relates to a packaging unit (4) comprising the support plate (1).

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